



# Product data sheet

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Applications General rectification

#### Features

- Small power mold type. (PMDU)
- Low IR.
- High reliability

Construction

Silicon epitaxial planer

- 14-

0-

-0

### Absolute maximum ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit
Reverse voltage (repetitive peak)	V <sub>RM</sub>	30	V
Reverse voltage (DC)	VR	30	V
Average rectified forward current	lo	1	A
Forward current surge peak (60Hz / 1cyc)	I <sub>FSM</sub>	30	A
Junction temperature	Tj	125	٥C
Storage temperature	Tstg	-40 to +125	°C

(\*1)Mounted on epoxy board. 180° Half sine wave

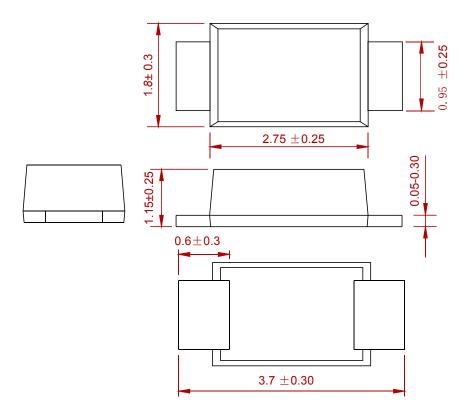
## Electrical characteristic (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
	V <sub>F</sub> 1	-	0.39	0.46	V	I⊧=0.5A
Forward voltage	V <sub>F</sub> 2	-	0.43	0.48	V	I <sub>F</sub> =1.0A
Reverse current	I <sub>R</sub> 1	-	3.0	20	μA	V <sub>R</sub> =15V
	I <sub>R</sub> 2	-	9.0	50	μA	V <sub>R</sub> =30V



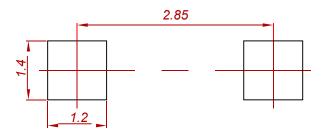


## PACKAGE MECHANICAL DATA



Dimensions in millimeters

## Suggested Pad Layout



#### Note:

1.Controlling dimension:in millimeters.

2.General tolerance:±0.05mm.

3. The pad layout is for reference purposes only.

## **REEL SPECIFICATION**

P/N	PKG	QTY
RB160M-30	SOD-123FL	3000



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